

Two Major Methods to Control Thermal Resistance of Focus Ring for Process Uniformity Enhance

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Abstract : Recently, the semiconductor industry is rapidly demanding complicated structures and mass production. From the point of view of mass production, the ETCH industry is concentrating on maintaining the ER (Etch rate) of the wafer edge constant regardless of changes over time. In this study, two major thermal factors affecting process were identified and controlled. First, the filler of the thermal pad was studied. Second, the significant difference of handling the thermal pad during PM was studied.

Keywords : etcher, thermal pad, wet cleaning, thermal conductivity

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